ECO SOLDER

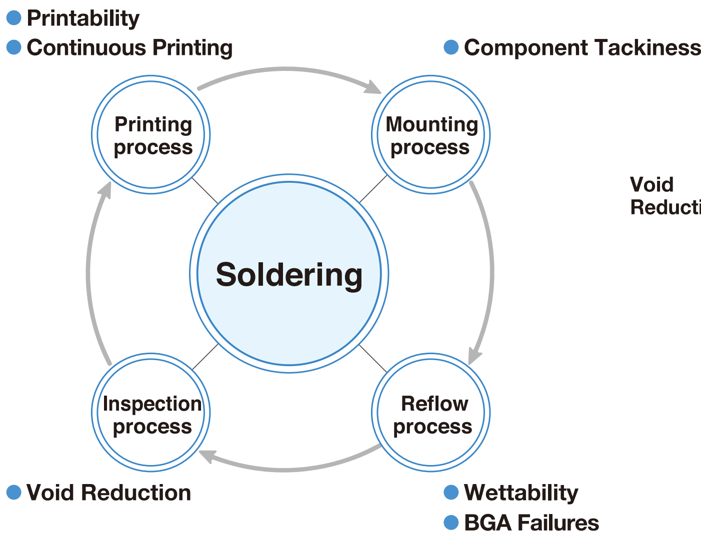
Solder Paste ULT369

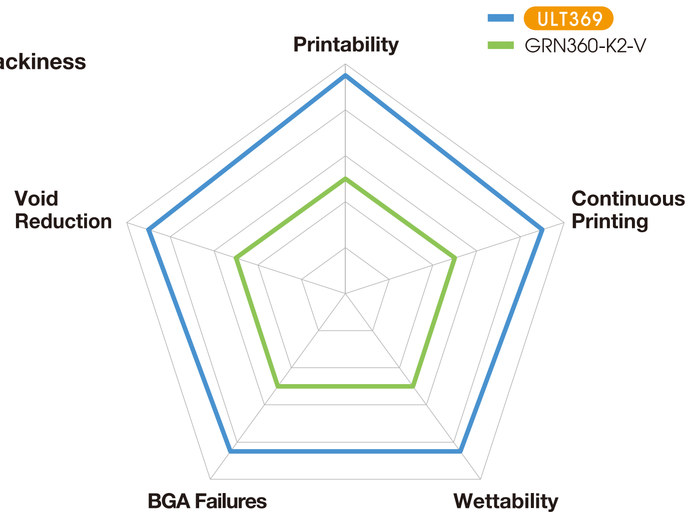
New Standard Products through SMT Process Feedback

Features

- Improve continuous printing and reduce amount of waste
- Suppress BGA unfused solder and non-wet open (NWO)
- Improved liquidity of flux during solder melting for reducing voids

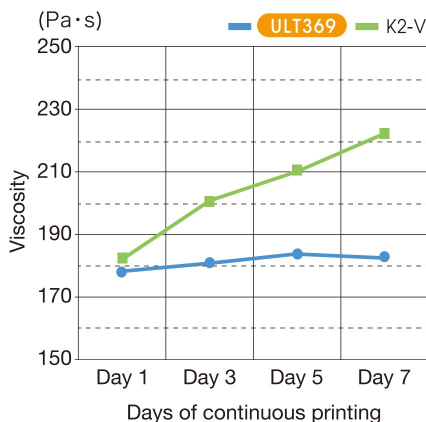
Revolutionary Products





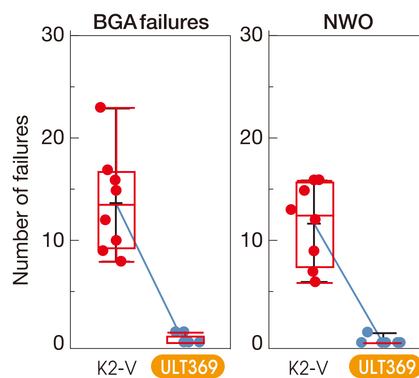
Improve continuous printing

Protect reaction of solder powder and flux during printing. Improve stencil life to reduce solder paste waste.



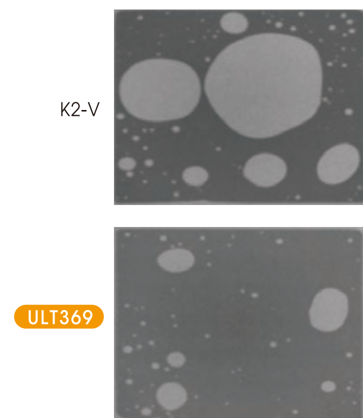
Suppress BGA failures and NWO

Suppress BGA failures and NWO by reassessing solder and pad reaction and increasing flux thermal resistance.



Void reduction

Reduce voids by improving liquidity of flux after solder melting.



SMIC